

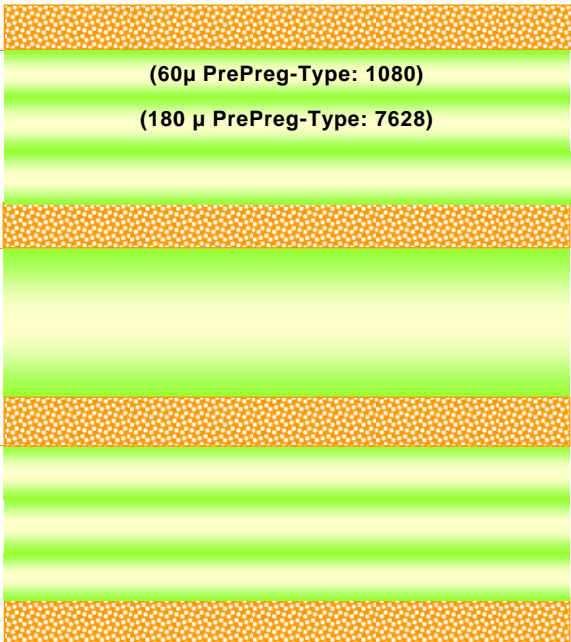
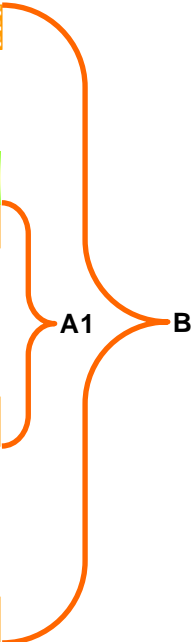
Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 196 FR4 60 L93.35 P06_18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_196_FR4_60_L93.35_p06_18

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	60 μ	Copper			
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)
	180 μ	Prepreg			(180 μ PrePreg-Type: 7628)
	180 μ	Prepreg			
Layer-2	35 μ	Copper			A1
	930 μ	L-FR4			
Layer-3	35 μ	Copper			B
	180 μ	Prepreg			
	180 μ	Prepreg			
	60 μ	Prepreg			
Layer-99	60 μ	Copper			

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